

# MOS FIELD EFFECT TRANSISTOR $\mu$ PA1759

## SWITCHING N-CHANNEL POWER MOS FET INDUSTRIAL USE

### **DESCRIPTION**

This product is Dual N-channel MOS Field Effect Transistor designed for DC/DC converters.

### **FEATURES**

- · Dual chip type
- Low on-resistance

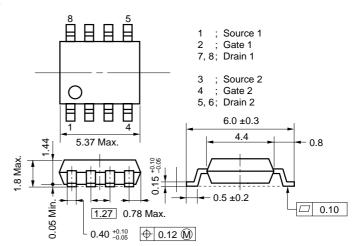
RDS(on)1 = 110 m $\Omega$  TYP. (VGs = 10 V, ID = 2.5 A) RDS(on)2 = 170 m $\Omega$  TYP. (VGs = 4 V, ID = 2.5 A)

- Low input capacitance Ciss = 190 pF TYP.
- Built-in G-S protection diode
- Small and surface mount package (Power SOP8)

## **ORDERING INFORMATION**

PART NUMBER	PACKAGE
μPA1759G	Power SOP8

## **PACKAGE DRAWING (Unit: mm)**

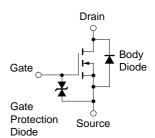


## ABSOLUTE MAXIMUM RATINGS (TA = 25 °C, All terminals are connected.)

Drain to Source Voltage (Vgs = 0)	VDSS	60	V
Gate to Source Voltage (VDS = 0)	Vgss	±20	V
Drain Current (DC)	ID(DC)	±5.0	Α
Drain Current (pulse) Note1	ID(pulse)	±20	Α
Total Power Dissipation (1 unit) Note2	Рт	1.7	W
Total Power Dissipation (2 unit) Note2	Рт	2.0	W
Channel Temperature	Tch	150	°C
Storage Temperature	Tstg	-55 to + 150	°C
Single Avalanche Current Note3	las	2.5	Α
Single Avalanche Energy Note3	Eas	0.625	mJ

## EQUIVALENT CIRCUIT

(1/2 Circuit)



- **Notes 1.** PW  $\leq$  10  $\mu$ s, Duty cycle  $\leq$  1 %
  - 2. Mounted on ceramic substrate of 1200 mm<sup>2</sup> x 1.7 mm
  - 3. Starting Tch = 25 °C, RG = 25  $\Omega$ , VGS = 20 V  $\rightarrow$  0 V

**Remark** The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

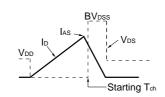


## ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, All terminals are connected.)

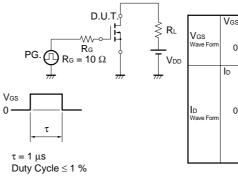
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Drain to Source On-state Resistance	RDS(on)1	V <sub>G</sub> S = 10 V, I <sub>D</sub> = 2.5 A		110	150	mΩ
	RDS(on)2	Vgs = 4 V, ID = 2.5 A		170	240	mΩ
Gate to Source Cut-off Voltage	V <sub>GS(off)</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	1.0	1.7	2.5	V
Forward Transfer Admittance	yfs	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 2.5 A	2.0	3.9		S
Drain Leakage Current	IDSS	Vps = 60 V, Vgs = 0 V			10	μΑ
Gate to Source Leakage Current	Igss	V <sub>G</sub> S = ±20 V, V <sub>D</sub> S = 0 V			±10	μΑ
Input Capacitance	Ciss	V <sub>DS</sub> = 10 V		190		pF
Output Capacitance	Coss	V <sub>GS</sub> = 0 V		100		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		36		pF
Turn-on Delay Time	td(on)	ID = 2.5 A		6		ns
Rise Time	tr	V <sub>GS(on)</sub> = 10 V		50		ns
Turn-off Delay Time	td(off)	V <sub>DD</sub> = 15 V		80		ns
Fall Time	tf	$R_G = 10 \Omega$		50		ns
Total Gate Charge	Q <sub>G</sub>	ID = 5.0 A		8		nC
Gate to Source Charge	Qgs	V <sub>DD</sub> = 24 V		1		nC
Gate to Drain Charge	Q <sub>GD</sub>	Vgs = 10 V		2.4		nC
Body Diode forward Voltage	V <sub>F</sub> (S-D)	I <sub>F</sub> = 5.0 A, V <sub>GS</sub> = 0 V		0.9		V
Reverse Recovery Time	trr	IF = 5.0 A, VGS = 0 V		40		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		50		nC

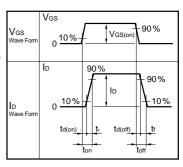
## **TEST CIRCUIT 1 AVALANCHE CAPABILITY**

# $\begin{array}{c} \text{D.U.T.} \\ \text{Rg} = 25 \Omega \\ \text{VGS} = 20 \rightarrow 0 \text{V} \end{array} \begin{array}{c} \text{PG.} \\ \text{W} \\ \text{W} \end{array} \begin{array}{c} \text{S} \\ \text{T} \\ \text{W} \end{array} \begin{array}{c} \text{VDD} \\ \text{W} \end{array}$



## **TEST CIRCUIT 2 SWITCHING TIME**





## **TEST CIRCUIT 3 GATE CHARGE**

[MEMO]

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